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U.S. Patent Documents

Examiner Initial	Document Number	Date	Patentee/Applicant	Class	Subclass	Filing Date if Appropriate
GA	2,905,805	9/22/1959	T. McElrath et al.			
GA	4,300,034	11/10/1981	Schneider et al.			
GA	5,081,334	1/14/1992	Copher et al.			
GA	5,196,664	3/23/1993	McGushion			
GA	5,227,609	7/13/1993	Simon et al.			
GA	5,313,039	5/17/1994	Harvey et al.			
GA	5,550,348	8/27/1996	Masaie et al.			
GA	6,140,607	10/31/2000	Kamada et al.			
GA	6,414,269	7/2/2002	Kim			

Foreign Patent Documents

Examiner Initial	Document Number	Publication Date	Country/Agency	Class	Subclass	Translation	
						Yes	No

Other Documents (Including Author, Title, Date, Pertinent Pages, Place of Publication, Etc.)

GA	Paul M. Bhadha, "How Weld Hose Materials Affect Shielding Gas Quality", AWS Welding Journal, Pgs. 35-40, July 1999
GA	"Rubber and Elastomer Piping Systems", Engineering Manual, U.S. Army Corps of Engineers, EM 1110-1-4008, Pgs. 6-1 to 6-5, 5 May 1999
GA	"Elastomers", 11 th Edition of the Material Handbook, Pgs. 168-274, April 29, 2003
GA	E. Farish, "Atmospheric Contamination of TIG Welding Gas Hoses - Causes and Cures", Welding & Metal Fabrication, Pgs. 300-301, July 1994
GA	"Industrial Hose Products", Brochure of Parker Industrial Hose Division, 2002 Parker Hannifin Corp., Publication No. PRB 4800-Welding, June 2002
GA	"Tungsten Excerpt 052303", Specification for Tungsten and Tungsten Alloy Electrodes for Arc-Welding and Cutting, ANSI/AWS, A5.12-92 (undated)

Examiner **C. SHAW**

Date Considered **3/6/2006**

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